

## ■ WL-CSP Marking System

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**LD-pumped fiber-coupling SHG laser marker with air cooling.**

### Features

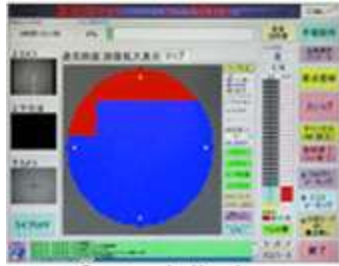
This system is equipped with SHG lasers that cause little damage to the workpieces. Since most of the laser light is absorbed on the wafer surface, the circuits suffer little damage. It can handle wafers of 6, 8, and 12 inches in size (150, 200, and 300 mm).

The system's fully digital controlled galvo-scanners provide high precision marking.

Its air-cooled laser markers (diode laser pumped type) make it easy to perform maintenance, resulting in lower running costs. We provide optional functions for auto focusing and vacuum-sucking glass stages to avoid warping the wafers.

We also offer a wide variety of options, such as Laser Power Feedback Control and ID reading.

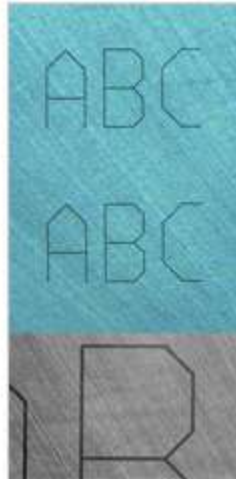
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- Fully air-cooled diode-pumped fiber-coupling SHG laser markers
  - Handles wafers of 6, 8, and 12 inches (150, 200, and 300 mm)
  - High-precision compensated marking
  - High-quality black marking and white marking
  - Options for measures to prevent wafer warping (vacuum-sucking glass stages; auto-focusing functions)



Control display



Sample wafer



Black marking  
(Melted hair lines)



White marking  
(Evaporated by strong pulse)

## Specifications

Model	MS-WL-6891 (for 6 to 8 inch), MS-WL-8291 (for 8 to 12 inch)
Dimensions and weight	2200W x 1763D x 1800H mm / 1600kg
Wafer size	12 inch: FOUP x1 8 inch: Full automation (Open cassette) x1 6 inch: Semi automation (Manually set to a table)
Thickness	0.3 to 2mm
Marking check	Automation (Black/white)
Marking positioning accuracy	Within +/- 50µm
Marking	White / black marking